PRESS RELEASE

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Heraeus Electronics Showcases Sustainable Semiconductor Materials at SEMICON Southeast Asia 2025

Celebrating 40 Years of Innovation in Singapore with Cutting-Edge Advanced Packaging Solutions: Materials. Innovations. For Generations.

Singapore, 20 – May 2025 – Heraeus Electronics, a leading global supplier of semiconductor materials, will exhibit at SEMICON Southeast Asia 2025, spotlighting its sustainable and high-performance solutions for advanced packaging. This year’s participation is especially meaningful as Heraeus Materials Singapore Pte Ltd celebrates 40 years of operations—marking four decades of innovation, manufacturing excellence, and customer collaboration in the region.

As part of its commitment to driving sustainability in semiconductor manufacturing, Heraeus Electronics will feature recycled gold bonding wires and recycled tin solder pastes, contributing to more circular production without compromising on quality or performance. These initiatives underscore Heraeus’ ongoing drive to provide responsible, future-forward material solutions for the electronics industry.

“We are proud to celebrate our 40th year in Singapore—a key hub for Heraeus in Asia and a center of excellence for our innovation,” said Li-San CHAN, Global Head of Business Line – Semiconductor Materials at Heraeus Electronics. “As the semiconductor industry moves toward miniaturization and greener manufacturing, Heraeus Electronics continues to support our global customers with reliable, sustainable, and advanced materials.”

Key Highlights at Heraeus Booth

SEMICON Southeast Asia 2025 | Sands Expo and Convention Centre, Singapore | Booth L1115

- **WELCO™ AP520 Solder Paste** – Enabling ultra-fine (down to 90µm) pitch all-in-one printing with low void and no splashing/beading for miniaturized electronic devices.
- **AP500X/AP501 Fluxes** – Offering outstanding zero-defect flip chip attach and excellent cleanability and eliminates pre-clean step for copper OSP pads.

- **Recycled Material Solutions** – Including recycled gold bonding wires and tin solder pastes, contributing to industry sustainability goals.
- **Vertical Wire Bonding Materials** – Designed to meet complex 3D IC and advanced packaging requirements.

Commitment to the Industry

With a strong presence in globally, Heraeus Electronics continues to drive innovations in packaging materials that meet the growing demand for miniaturization, performance, and sustainability.

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About Heraeus Electronics

Heraeus Electronics, part of the Heraeus Group headquartered in Germany, is a global leader in material solutions for the semiconductor and electronics industry. Its portfolio supports advanced applications in automotive, mobile devices, consumer electronics, and industrial systems. With a network of R&D and production facilities worldwide, Heraeus enables next-generation electronics with precision and sustainability.